

June 2020





















Chip varistors

Voltage Protection Devices

Automotive grade



AVRM, AVR-M series

AVRM1608/AVR-M1608 JIS 1608 [EIA 0603] AVRM2012/AVR-M2012 JIS 2012 [EIA 0805]

AVRL series

AVRL10 JIS 1005 [EIA 0402] **AVRL16** JIS 1608 [EIA 0603]

AVRH series

AVRH10 JIS 1005 [EIA 0402]

公TDK

Chip varistors

Automotive grade

Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

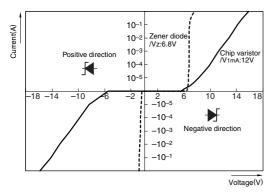
Overview of the AVR series

CHARACTERISTICS OF CHIP VARISTOR

Varistors are voltage dependent nonlinear resistive elements with a resistance that decreases rapidly when the voltage is over the constant value.

Varistors become zener diode of 2 serial connection and equivalent, and does not have polarity.

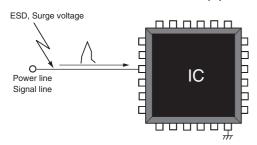
CURRENT vs. VOLTAGE CHARACTERISTICS



☐THE EFFECT OF THE VARISTOR

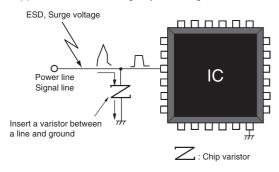
Without varistor

A malfunction and failure of electronic equipment



With Varistor

Suppress transient voltage by inserting varistor in a circuit



EQUIVALENT CIRCUIT OF CHIP VARISTORS

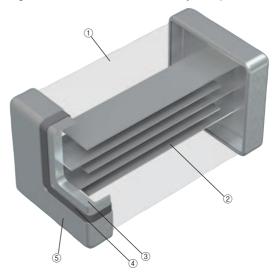


CHIP VARISTORS FEATURE FOR AUTOMOTIVE

GRADE

- Reliability characteristics evaluated based on AEC-Q200 condition
- O High ESD withstanding voltage
- Small-sized products are available
- 125°C, 150°C Supported

Figure 1 internal structure of multilayer chip varistors



No.	Name	
(1)	Semiconductor ceran	nic
(2)	Internal electrode(Pd)
(3)		Ag
(4)	Terminal electrode	Ni
(5)	_	Sn



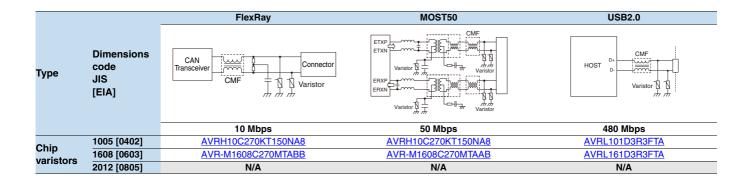
Automotive grade

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Overview of the AVR series

■ COMMUNICATION STANDARD, CIRCUIT EXAMPLE AND COMMUNICATION STANDARD

		LIN/CXPI	Classical CAN	CAN/CAN-FD
Туре	Dimensions code JIS [EIA]	LIN/CXPI Transceiver Coil, Bead Connector Varistor	CAN Transceiver Connector CMF Varistor	CAN Transceiver Connector Connector Varistor
		20 kbps	1 Mbps	2-8 Mbps
Chin	1005 [0402]	N/A	AVRH10C270KT150NA8	AVRH10C270KT150NA8
Chip varistors	1608 [0603]	AVRM1608C270KT221M	AVR-M1608C270MTAAB	AVR-M1608C270MTABB
varistors	2012 [0805]	N/A	N/A	N/A



		One-Pair Ethernet 100BASE-T1	One-Pair Ethernet 1000BASE-T1	Motors
Туре	Dimensions code JIS [EIA]	100BASE-T1 Connector Varistor \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	1000BASE-T1 Connector Varistor \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	•Varistor (ESD)
		100Mbps	1000Mbps	-
Chip	1005 [0402]	AVRH10C101KT4R7FA8	<u>AVRH10C101KT1R1NE8</u> <u>AVRH10C221KT1R5YA8</u>	N/A
varistors	1608 [0603]	N/A	N/A	AVR-M1608C270KT6AB
	2012 [0805]	N/A	N/A	AVR-M2012C390KT6AB

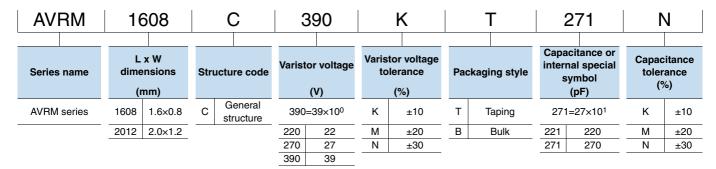


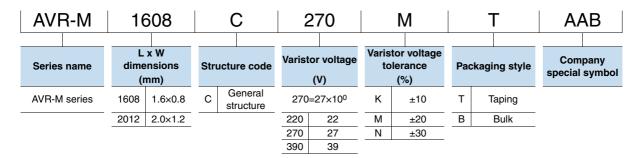
Chip varistors Automotive grade

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Overview of the AVR series

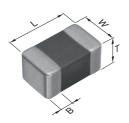
PART NUMBER CONSTRUCTION





AVRL		10		1A	3	R3		F		Т	Α
									•		
Series name	dim	. x W ensions mm)	-	Maximum nuous voltage (Vdc)		acitance (pF)	•	acitance lerance (pF)	Pac	kaging style	Company special symbol
AVRL series	10	1.0×0.5	1A	10	3R3	3.3	F	±1	Т	Taping	
L=Low cap	16	1.6×0.8			6R8	6.8	G	±2	В	Bulk	

	AVI	RH		10		С	2	70		K		T	1	50		N	•	4		8
	Series	name	dim	. x W ensions		tructure code	vol	istor tage	vo	ristor Itage erance	Pacl	kaging style	•	citance	•	acitance lerance	amo	oltage ount 000-4-2	temp li	erating erature mit
			(mm)			(V)	((%)			(r	F)			(k	V)	(°C)
	AVRH	series	10	1.0×0.5	С	General structure	270=	27×10 ⁰	K	±10	Т	Taping	150=1	15×10 ⁰	N	±30%	Α	25	8	150
Ī	H=High F	Reliability					270	27			В	Bulk	150	15	F	±1pF				
							390	39					500	50						
							101	100					4R7	4.7						



Shape symbol(JIS)	L	W	Т	В
1005	1.00±0.05	0.50±0.05	0.50±0.05	0.1min.
1608	1.60±0.1	0.80±0.1	0.80±0.1	0.2min.
2012	2.00±0.2	1.25±0.2	1.00±0.2	0.2min.

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Automotive grade

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Overview of the AVR series

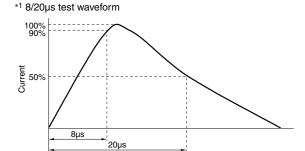
■ OPERATING TEMPERATURE RANGE, PACKAGE QUANTITY, PRODUCT WEIGHT

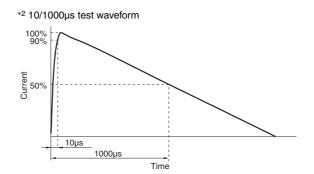
	Temperat	ure range	Package quantity	Individual weight
Туре	Operating temperature* (°C)	Storage temperature** (°C)	(pieces/reel)	(mg)
AVRM1005 AVR-M1005 AVRL10	-40 to +125	-40 to +125	10,000	1.2
AVRH10	-55 to +150	-55 to +150		
AVRM1608 AVRL16 AVR-M1608	-40 to +125	-40 to +125	4,000	5
AVR-M2012			2,000	13

^{*} Operating temperature range includes self-temperature rise.

TERMINOLOGY

Item	Unit	Description
Varistor voltage	V1mA	Chip varistor-terminal voltage when DC1mA was flowed
(Breakdown voltage)	(V)	Doubles that is self-continued and indicate the continued and
Maximum continuous voltage	Vdc	DC voltage that is continuously applied between chip varistor terminals Terminal chip varistors leakage current-value: 50µA max
3	(V)	Voltage appearing across the varistor when a pulse current (8/20µs*1) of specified peak value is applied.
Clampingualtage	Vcl	Voltage between terminal chip varistors of the Specified peak current value of the impulse current(8/
Clamping voltage	(V)	20μs*1) is applied
Maximum anaray	E	When applied specified peak impulse current-value current(10/1000μs*²) once, maximum energy that
Maximum energy	(Joule)	electrical property of chip varistors be not deteriorated
Maximum pook aurrent	lp	When applied impulse current(8/20µs*1) once, maximum current that electrical property of chip varistors
Maximum peak current	(A)	be not deteriorated
Conscitones	С	Oscillator frequency 1kHz or 1MHz, Capacitance between chip varistor-terminal in oscillator voltage
Capacitance	(PF)	1Vrms





^{**} The storage temperature range is for after the assembly.

Voltage Protection Devices



Chip varistors Automotive grade

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AVR series (Automotive grade) Product characteristics list

■ PRODUCT CHARACTERISTICS LIST

Item	Size	V (1mA)	C1kHz *C1MHz	Vdc	Clamping voltage 8/20µs Pulse	Maximum energy 10/1000µs Pulse	Maximum peak current 8/20µs Pulse	IEC61000-4-2 (Contact)	AEC- Q200
	(mm)	(V)	(pF)	DC (V)	Vcl (V)		Ip (A)	150pF/330 Ω	
AVRL101D3R3FTA	1.0 x 0.5 (EIA0402)	27(21.6 to 32.4)	3.3(2.3 to 4.3)*	20	62(0.5A)	0.01	0.5	8kV	v
AVRL101D6R8GTA	1.0 x 0.5 (EIA0402)	27(21.6 to 32.4)	6.8(4.8 to 8.8)*	20	58(1A)	0.01	1	8kV	V
AVRH10C270KT150NA8	1.0 x 0.5 (EIA0402)	27(24.0 to 30.0)	15(10.5 to 19.5)	19	52(2A)	0.02	2	25kV	V
AVRH10C270KT350NA8	1.0 x 0.5 (EIA0402)	27(24.0 to 30.0)	35(24.5 to 45.5)	19	52(2A)	0.02	8	25kV	V
AVRH10C390KT500NA8	1.0 x 0.5 (EIA0402)	39(35.0 to 43.0)	50(35 to 65)	28	72(2A)	0.02	15	25kV	V
AVRH10C101KT4R7FA8	1.0 x 0.5 (EIA0402)	100(90 to 110)	4.7(3.7 to 5.7)*	70	190(1A)	0.03	1	25kV	V
AVRH10C101KT1R1NE8	1.0 x 0.5 (EIA0402)	110(100 to 120)	1.1(0.8 to 1.4)*	70	190 (0.3A)	0.01	0.3	8kV	V
AVRH10C221KT1R5YA8	1.0 x 0.5 (EIA0402)	220 (198 to 242)	1.5(1.37 to 1.63)*	70	400 (0.5A)	0.01	0.5	25kV	
AVRL161D3R3FTA	1.6 x 0.8 (EIA0603)	27(21.6 to 32.4)	3.3(2.3 to 4.3)*	20	62(0.5A)	0.01	0.5	8kV	V
AVRL161D6R8GTA	1.6 x 0.8 (EIA0603)	27(21.6 to 32.4)	6.8(4.8 to 8.8)*	20	58(1A)	0.01	1	8kV	V
AVR-M1608C220KT2AB	1.6 x 0.8 (EIA0603)	22(19.8 to 24.2)	210(147 to 273)	16	37(2A)	0.03	10	25kV	V
AVR-M1608C220KT6AB	1.6 x 0.8 (EIA0603)	22(19.8 to 24.2)	560(392 to 728)	16	34(2A)	0.10	30	25kV	V
AVR-M1608C270MTABB	1.6 x 0.8 (EIA0603)	27(21.6 to 32.4)	15(10.5 to 19.5)	17	52(2A)	0.05	2	25kV	V
AVR-M1608C270MTAAB	1.6 x 0.8 (EIA0603)	27(21.6 to 32.4)	30(21 to 39)	17	52(2A)	0.05	2	25kV	V
AVR-M1608C270KTACB	1.6 x 0.8 (EIA0603)	27(24.0 to 30.0)	60(42 to 78)	19	54(2A)	0.05	10	25kV	V
AVRM1608C270KT800M	1.6 x 0.8 (EIA0603)	27(24.0 to 30.0)	80(64 to 96)	19	53(2A)	0.02	28	25kV	V
AVR-M1608C270KT2AB	1.6 x 0.8 (EIA0603)	27(24.0 to 30.0)	160(112 to 208)	19	42(2A)	0.10	20	25kV	V
AVRM1608C270KT221M	1.6 x 0.8 (EIA0603)	27(24.0 to 30.0)	220(176 to 264)	19	52(2A)	0.10	40	25kV	V
AVR-M1608C270KT6AB	1.6 x 0.8 (EIA0603)	27(24.0 to 30.0)	430(301 to 339)	19	42(2A)	0.10	48	25kV	V
AVRM1608C390KT271N	1.6 x 0.8 (EIA0603)	39(35.0 to 43.0)	270(189 to 351)	28	69(2A)	0.10	78	25kV	V
AVRM1608C560KT101M	1.6 x 0.8 (EIA0603)	56(50.4 to 61.6)	100(80 to 120)	40	113(2A)	0.10	60	25kV	~
AVRM1608C720KT750M	1.6 x 0.8 (EIA0603)	72(64.8 to 79.2)	75(60 to 90)	53	135(2A)	0.10	40	25kV	V
AVR-M2012C220KT6AB	2.0 x 1.2 (EIA0805)	22(19.8 to 24.2)	800(560 to 1040)	16	38(5A)	0.30	100	25kV	V
AVRM2012C330KT801N	2.0 x 1.2 (EIA0805)	33(29.7 to 36.3)	800(560 to 1040)	24	59(5A)	0.50	240	25kV	V
AVR-M2012C390KT6AB	2.0 x 1.2 (EIA0805)	39(35.0 to 43.0)	430(301 to 559)	28	62(5A)	0.30	100	25kV	~
AVRM2012C560KT251M	2.0 x 1.2 (EIA0805)	56(50.4 to 61.6)	250(200 to 300)	40	113(5A)	0.30	150	25kV	V
AVRM2012C720KT201M	2.0 x 1.2 (EIA0805)	72(64.8 to 79.2)	200(160 to 240)	53	142(5A)	0.30	100	25kV	~

Voltage Protection Devices



Chip varistors

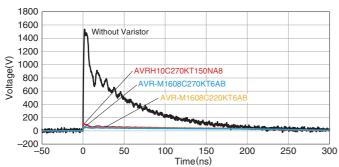
Automotive grade

Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

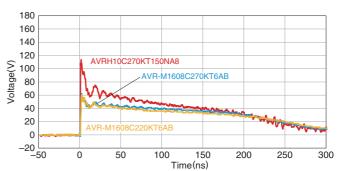
AVR series Electrostatic absorption characteristics

■ DISCHARGE VOLTAGE WAVEFORM (EXAMPLE)

\square WITHOUT VARISTOR, WAVEFORM AT VARISTOR INSTALLATION

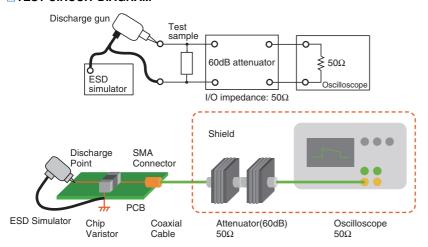


WAVEFORM AT VARISTOR INSTALLATION



□Test conditions 150 pF/330 Ω (IEC61000-4-2) Contact discharge, Charged voltage 8kV

□TEST CIRCUIT DIAGRAM





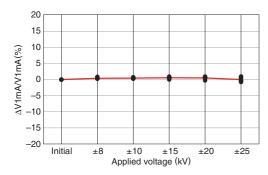
Automotive grade

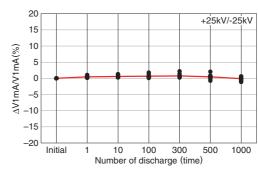
Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

AVR series Electrostatic discharge tests

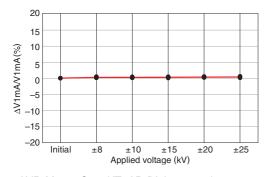
■ APPLIED VOLTAGE STEP(VOLTAGE 10TIMES APPLIED) ■ REPEATED VOLTAGE APPLICATION(~1000 times)

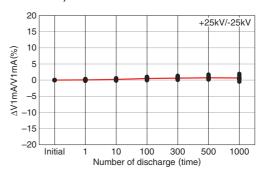
□AVRH10C270KT150NA8 (Voltage % change at reference current: within ±10%)



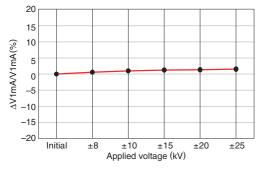


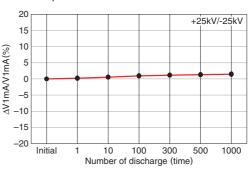
□AVR-M1608C270MTAAB (Voltage % change at reference current: within ±10%)



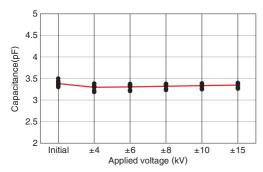


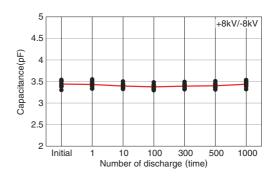
□AVR-M2012C390KT6AB (Voltage % change at reference current: within ±10%)





□AVRL101D3R3FTA(Capacitance: 5pF or less)





^{*} ESD condition: 150pF/330 Ω (IEC61000-4-2)

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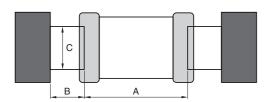
Attention on a circuit board design

Board design

When attached to chip varistors, amount of silver used (fillet size) has direct impact on chip varistors after mounting. Thus, sufficient consideration is necessary.

Set of land dimensions

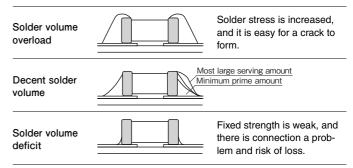
(1) As the stress rises in the chip varistors owing to the increase in silver, breakage and cracks will occur. Cause including crack, as caution on board land design, configure the shape and dimensions so that the amount of silver is appropriate. If you installed 2 or more parts in the Common Land, separated by a solder resist and special land of each component.



Dimensions shape	Symbol						
Difficitsions shape	A	В	С				
1005	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60				
1608	0.60 to 0.80	0.60 to 0.80	0.60 to 0.80				
2012	0.90 to 1.20	0.70 to 0.90	0.90 to 1.20				

(2) When peak levels panning-at soldering is excessive, by solder contraction stress, mechanical-thermal stress causes a Yasuku chip crack. In addition, when the peak level is underestimated, terminal electrode fixed strength is insufficient. This causes chip dropouts and may affect circuit reliability. Representative example of the panning of peak levels is shown in the following.

Recommended silver dose



Case and suggested protocol want to avoid

Example	Cases to avoid	Improvement example (land division)
Lead wire and land of part discrete doubles up	Leads Chip Solder	Solder resist Leads
Arrangements in the vicinity	Chassis Solder (ground solder)	Solder resist L2 L2>L1
Arrangements of chip component's companion	Excess solder Land Missing solder	Solder resist



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Attention on a circuit board design

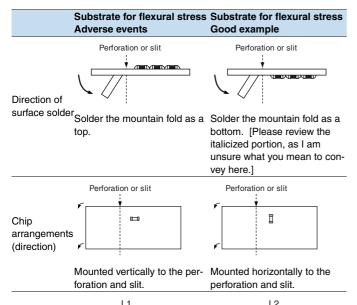
Arrangements of components

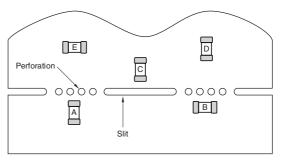
perforation and slit

portion

(1) I was based on camber of substrate and suggested protocol of chip varistors arrangement, as stress does not join to the utmost is shown in following.

(2) In payment near by board, depending on mount position of chip varistors, as mechanical stress varies, please refer to the following diagram.





The order of A > B = C > D > E eases the stress.

Distance from (L1<L2) (L1<L2) Close location is disadvanta-It is an advantage so distant

location away places the perfo-

ration and slit

geous of perforation and slit.

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Chip varistors

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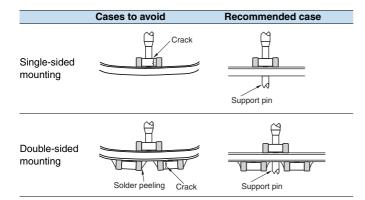
Local precautions

Application to board

Mounting head pressure

Under suction nozzle if dead point too, during implementation, excessive force joins of chip varistors low, as cause causes of crack, please use with reference to something about following.

- Being set to top surface of substrate so that under suction nozzle as for dead center, substrate does not bend back, and adjust, please.
- 2) Nozzle pressure at implementation is 0.1 to 0.3N in static load, please.
- 3) Substrate fixes up back surface of substrate with support pin in impact of suction nozzle to wely deflection to the utmost, and substrate hold deflection, please. A representative example is shown in the following.



Mechanical shock that, if positioning your nail to wear, ragged edge of positionings, participates in chip varistors are locally, and chip varistors, as there is possibility of crack generated, cut the closed positioning, and maintenance and inspection, and, exchange of manage dimensions and position nail periodically, please.

Soldering

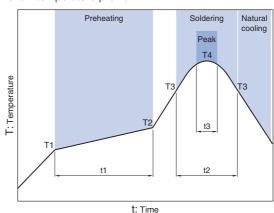
Significant impact is possible on the performance of chip varistors, flux checks something about follow, please use.

(1) Flux uses one with 0.1wt % (CI conversion) or less halide substance contains amounts, please. In addition, do not do this with strongly acidic objects.

Flux during is soldered (2) Chip varistors is applied the smalleset amount necessary, please.

(3) If Used soluble flux, perform thorough wash particularly, please.

Reflow temperature profile



	Specification	
Item	For eutectic mixture solder	Use of lead-free solder
Preheating temperature	160 to 180°C	150 to 180°C
Solder melting temperature	200°C	230°C
Maximum temperature	240°C max.	260°C max.
Preheating time	100s max.	120s max.
Time to reach higher than the solder melting temperature	30s max.	40s max.
number of possible reflow cycles	2 max.	2 max.

Soldering iron

The tip temperature and also by (1) types of soldering irons, the size of the substrate, and the geometry of the land pattern. Being earlier, but when as there is possibility that crack occurs in the heat anderson impaction, point soldering iron temperature is high, please do solder work within the following conditions.

Temperature of iron tips (°C)	Wattage (W)	Pallet point shape (mm)	Soldering time (Second)	Frequency
350max.	30max.	ø3.0max.	5 max.	Within each terminal once (Within total of twice)

Direct iron tip is in contact with the (2) chip varistors body, and the strain owing to thermal shock in particular grows even if a crack is generated. Therefore, please do not touch it directly to the terminal electrodes.

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Attention after implementation

Cleaning

(1) If cleaning liquid is inappropriate, residues and other foreign body of fluxes builds up on chip varistors, and can degrade the performance of chip varistors (particularly the insulation resistance).(2) Wash conditions may compromise performance of chip varistors if they are improper (wash due, wash excess).

2-1) For wash due

- (a) By substance of a system in flux residue halide, metal including terminal electrodes may experience corrosion.
- (b) Substance of a system in flux residue halide builds up on chip varistors, and reduces the insulation resistance.
- (c) Soluble flux makes comparisons of colophony series flux, and there is event with trends of significant (1) and(2).

2-2) For excess wash

- Owing to lavage, chip varistors deteriorates, and reduces performance of chip varistors.
- (2) In ultrasonography, when output is passed, substrate resonates size, and crack occurs in body and sprang of chip varistors in vibration of substrate. Since this may reduce the strength of the terminal electrode, please note the following conditions. [Please review the italicized portion, as I am unsure what you mean to convey here.]

Ultrasound output

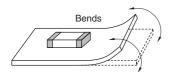
Ultrasonic frequency

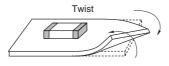
Ultrasound cleaning time

2-3) Concentration including halogen that when cleaning liquid to pollution, when you released is higher, and may cause similar of results into wash due.

Substrate handling after component mounting

(1) When substrate is divided, a flexible so that show in following diagram to substrate, and is given by stress including twist, as there is possibility that crack occurs of chip varistors, please check that stress is within acceptable limits.



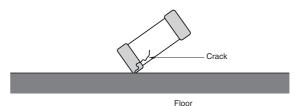


(2) During each substrate operational check, push pressure with contact failure of check pin of boards checkers of check pin may be toned up to be prevented. As substrate is bent under loading, chip varistors is broken owing to stress. There is also the possibility that solder on the terminal electrode will peel off. Follow the diagram for reference, and check that the substrate bends, please.

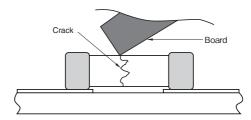
Item	Cases to avoid	Recommended case	
Substrate sags	Peeling Check pin	Support pin Check pin	

Single-part component handling

To drop impact, as there is possibility that breakage and crack is entered, do not chip varistors that(1) chip varistors falls.



(2) At stacking storage after implementation and treatment of substrate, corner of boards is regarded as chip varistors. Please be careful, as there is the possibility that breakage and cracks will occur on impact.



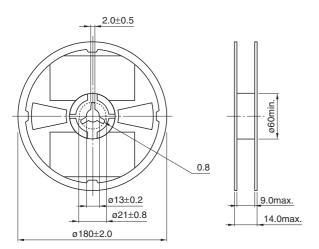


Automotive grade

Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

Packaging style

REEL DIMENSIONS

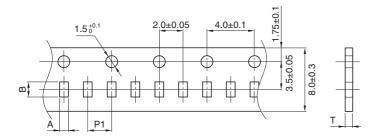


Dimensions in mm

■PACKAGE QUANTITY / INDIVIDUAL WEIGHT

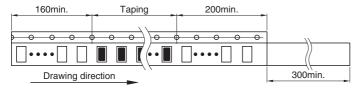
Туре	Package quantity	Individual weight	
Type	(pieces/reel)	(mg)	
1005	10,000	1.3	
1608	4,000	5.3	
2012	2,000	13.0	

■TAPE DIMENSIONS



Dimensions in mm

Туре	Α	В	P1	Т
1005	0.65+0.05/-0.1	1.15+0.05/-0.1	2±0.05	0.65max.
1608	1.1±0.2	1.9±0.2	4±0.1	1.1max.
2012	1.6±0.2	2.3±0.2	4±0.1	1.7max.



Dimensions in mm



REMINDERS FOR USING THESE PRODUCTS

Before using these products, be sure to request the delivery specifications.

SAFETY REMINDERS

Please pay sufficient attention to the warnings for safe designing when using this products.

⚠ REMINDERS

- OPlease pay careful attention to the precautions and follow safe designing practices when using these products.
- Please observe the following precautions in order to avoid problems with chip varistors such as characteristic degradation and element destruction

Please store these products in an environment with a temperature of 5 to 40°C and humidity level of 20 to 70%RH, and use them within six months.

Poor storage conditions may lead to the deterioration of the solderability of the edge electrodes, so please be careful to avoid contact with humidity, dew condensation, dust, toxic gas (hydrogen, hydrogen sulfide, sulfurous acid, chlorine, ammonia, etc.), direct sunlight, and so on

Please do not use products that have been dropped or detached when mounting.

Please solder with the reflow soldering method, and not the flow (dip) soldering method.

- Please observe the following precautions to avoid problems with varistors such as characteristic degradation and element destruction, which ultimately lead to the generation of heat and smoke with the elements.
 - Do not use in locations where the temperatures exceed the operating temperature range such as under direct sunlight or near sources of heat.

Do not use in locations where there are high levels of humidity such as under direct exposure to weather and areas where steam is released.

Do not use in locations such as dusty areas, high-saline environments, places where the atmosphere is contaminated with corrosive gas, etc.

Avoid powerful vibrations, impact (such as by dropping), pressure, etc. that may lead to splitting in the products.

Do not use with a voltage that exceeds the maximum allowable circuit voltage.

When resin coating (including modular) a varistor, do not use a resin that will cause deterioration of the varistor. Be sure never to use resin that generates hydrogen as palladium is used for the inner electrode.

Avoid attachment near combustible materials.

- Please contact our sales offices when considering the use of the products listed on this catalog for applications, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property ('specific uses' such as automobiles, airplanes, medical instruments, nuclear devices, etc.) as well as when considering the use for applications that exceed the range and conditions of this catalog.
 - Please also contact us when using these products for automotive applications.
- As range of catalog, conditions are transcended, or for damage that generated by was used in application specific, etc, accept no the responsibility, wish.
- Please take appropriate measures such as acquiring protective circuits and devices that meet the uses, applications, and conditions of the instruments and keeping backup circuits.

单击下面可查看定价,库存,交付和生命周期等信息

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